



# **Global Communication Semiconductors, LLC**

Corporate & Foundry

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Job Title: **Device / Process Integration Engineer**  
Job Req. #0563  
Department: Technology  
Status: Full-Time/Exempt

## **Job Description**

The Device / Process Integration Engineer covers increasing demand for the development and transfer of III-V HBT and other device technologies.

- Focuses on process development and yield improvement of InP, InGaP HBT and other III-V devices such as PIN diodes and possible process transfer of InGaP HBT process to other fabs.
- Covers device fabrication (including photolithography, thin film deposition and wet/dry etch), and device characterization (including DC/RF test, PCM, and data analysis).
- Responsible for process development, yield improvement, troubleshooting, process qualification, and process transfer for InGaP HBT or other III-V devices.

## **Job Requirements**

- MS or PhD in Electrical Engineering, Physics, Chemistry or Material Science, and 5+ years of experience in III-V semiconductor device R&D or manufacture.
- Must have good knowledge of semiconductor device physics, and experience in III-V wafer processing and characterization.
- Experience in InGaP or InP HBT, RF PIN diode is a plus.